

TIDA00891 - Test Results

1. GENERAL

1.1. **PURPOSE**

1.1.1. To provide detailed instructions for testing TIDA-00891 USB TypeCTM Plug to USB Type-A Receptacle SS MUX with UFP Controller Reference Design module.

1.2. **SCOPE**

1.2.1. This document describes the steps required to perform a general testing TIDA-00891 USB TypeCTM Plug to USB Type-A Receptacle SS MUX with UFP Controller Reference Design functional test.

1.3. REFERENCE DOCUMENTATION

- 1.3.1. Schematic TIDA-00891 SCH.DSN
- 1.3.2. Assembly TIDA-00891 PCB.brd
- 1.3.3. TIDA-00891 User's Guide.pdf

1.4. MATERIALS

• Type-C cable.

1.5. **DEFINITIONS**

- 1.5.1. USB Universal Serial Bus.
- 1.5.2. EVM Evaluation Module.
- 1.5.3. REV Revision.
- 1.5.4. UFP- Upstream Facing Port.
- 1.5.5. DFP- Downstream Facing Port.

2. EQUIPMENT

- 3220UFP-DGLEVM.
- 3220DFP-DGLEVM.
- USB3 capable host Type-A receptacle port.
- USB3 capable host Type-C receptacle port.
- Type-A USB UFP device.
- Type-C to Type-A adaptor.

3. <u>EQUIPMENT SETUP</u>

- 3.1. USB Connection Test.
 - 3.1.1. Connect the TIDA-00890 to a USB3 Type-A port.
 - 3.1.2. Connect TIDA-00891 to the DFP dongle via a USB Type-CTM cable.
 - 3.1.3. Upon connection, the green (D2) and orange (D7) LEDs should illuminate.
 - 3.1.4. Connect a USB3 device to the USB Type-A of the TIDA-00891. The device plugged in should enumerate.



The figure below describes an example configuration. Two test configurations are possible.

Configuration 1 shows the TIDA-00891 connected to a legacy USB host through a TIDA-00890 with a USB Type- C^{TM} port.

Configuration 2 shows USB host with a USB Type-C™ connector connected to the TIDA-00891.

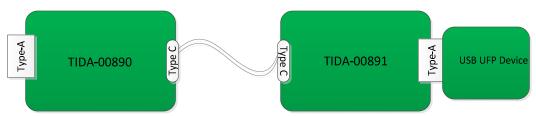


Figure 1. Test Configuration 1 with a USB Type-C™ DFP dongle

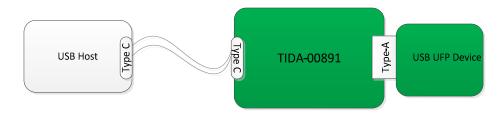


Figure 2. Test Configuration 2 with a USB Type-CTM Host

4. PROCEDURE

4.1. Check USB3 connection through **USB view** or **device manager** of the USB Host system. MUST verify connection is SUPER in both USB Type-C connection orientations.



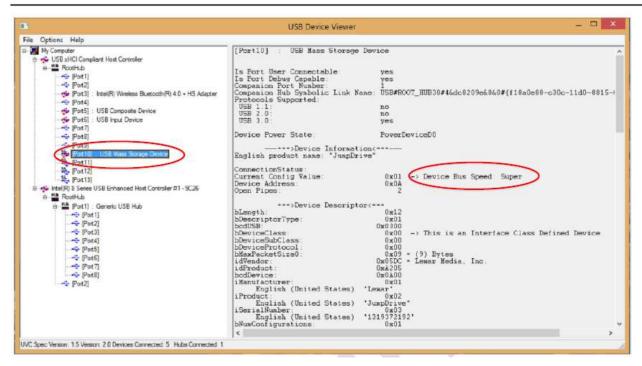


Figure 3. Checking USB connection Speed using USBVIEW

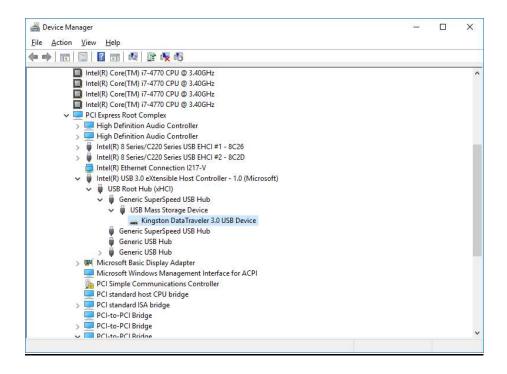


Figure 4. Checking USB connection using Device Manager

4.2. Connect a USB device to/through the Type-C receptacle port (J4) of the TIDA-00891 using either configuration described in Step 3.



4.3. Check USB2 connection though USB view or device manager of the USB Host System. Check USB2 connection in both USB Type-C orientations.



Figure 5. TIDA-00891 Test Setup example

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